

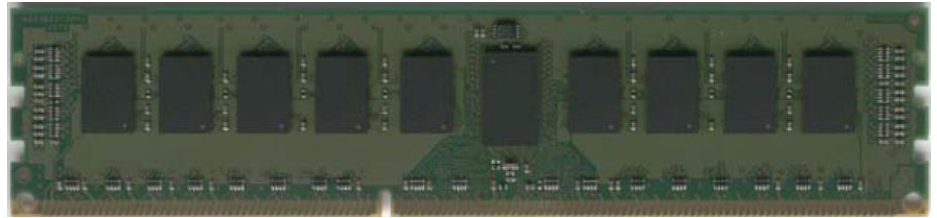
Identification

DVM18R2S4/16G 2Gx72
16GB 2Rx4 PC3-14900R-13

Performance Range

Clock / Module Speed / CL-t_{RCD}-t_{RP}

933 MHz / PC3-14900 / 13-13-13
800 MHz / PC3-14900 / 11-11-11
667 MHz / PC3-10600 / 10-10-10
667 MHz / PC3-10600 / 9-9-9
533 MHz / PC3-8500 / 8-8-8
533 MHz / PC3-8500 / 7-7-7
400 MHz / PC3-6400 / 6-6-6



Features

240-pin JEDEC-compliant DIMM, 133.35 mm wide by 30.00 mm high
Operating Voltage: VDD = VDDQ = +1.5V ±0.075V
I/O Type: SSTL_15
On-board I²C temperature sensor with integrated Serial Presence-Detect (SPD) EEPROM
Data Transfer Rate: 14.9 Gigabytes/sec
Data Bursts: 8 and burst chop 4 mode
ZQ Calibration for Output Driver and On-Die Termination (ODT)
Programmable ODT / Dynamic ODT during Writes
Programmable CAS Latency: 6, 7, 8, 9, 10, 11 and 13
Bi-directional Differential Data Strobe signals
SDRAM Addressing (Row/Col/BG/BA): 16/11/3
Fully RoHS Compliant

Description

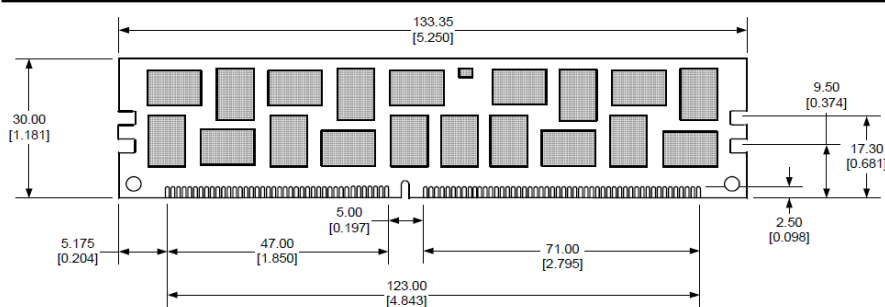
DVM18R2S4/16G is a registered 2Gx72 memory module, which conforms to JEDEC's DDR3-1866, PC3-14900 standard. The assembly is Dual-Rank. Each rank is comprised of nine 1Gbx4 DDR3 SDRAMs.

One EEPROM is used for Serial Presence Detect and a combination register/PLL, with Address and Command Parity, is also used.

Both output driver strength and input termination impedance are programmable to maintain signal integrity on the I/O signals in a Fly-by topology.

A thermal sensor accurately monitors the DIMM module and can prevent exceeding the maximum operating temperature of 95C.

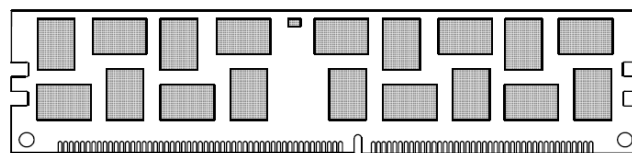
Front view



Notes

Tolerances on all dimensions except where otherwise indicated are ±.13 (.005). All dimensions are expressed in millimeters [inches]

Back view



Side view

